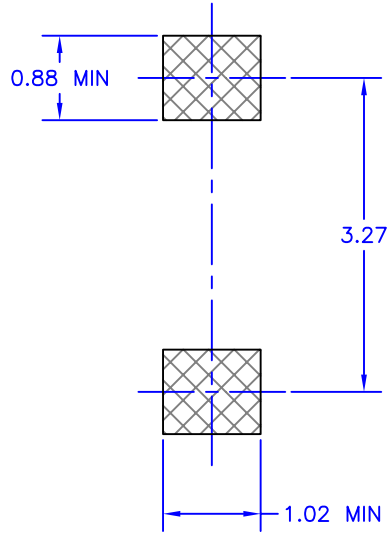
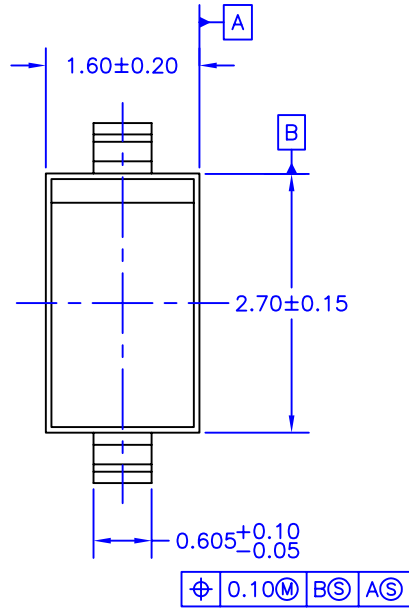
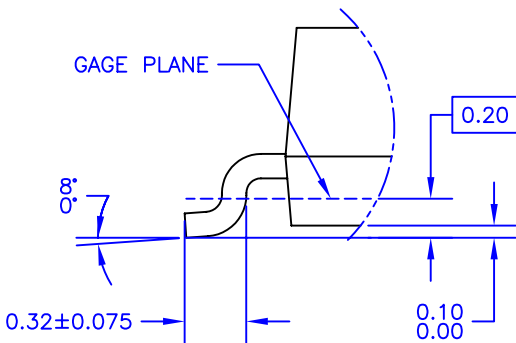
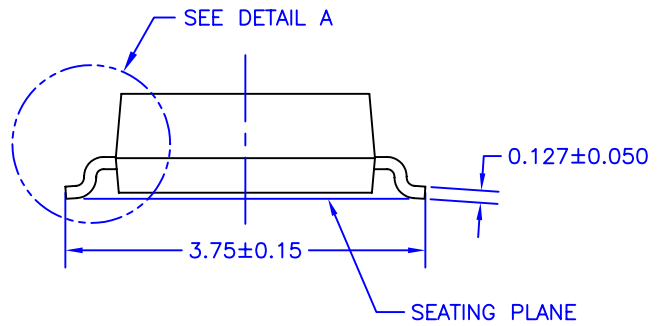
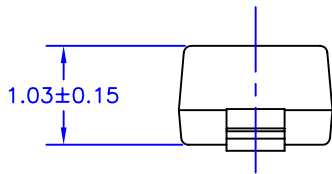


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REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	00100	JAN.3.2000	MRC
B	CHG LGHT FR 2.44 TO 2.7MM; CHG LD SPREAD DIM FR 3.70 TO 3.75MM; CHG FOOT LGHT DIM FR 0.427 TO 0.332MM; CHG FR 0.224 TO 0.119.	00100	JAN.3.2000	MRC
3	CHG DWG TEMPLATE FR OLD TO NEW STD; REMOVE COPLA GEOM TOLERANCE; CHG PROFILE DIM FR 8/32 TO 3/8; ADD NOTES; ADD GAGE PLANE; ADD FOOT ANGLE DIM; ADD FOOT LENGHT DIM. REMOVE SITE ADDRESS		04AUG2008	HYANG/FSSZ



LAND PATTERN RECOMMENDATION



DETAIL A
SCALE: 2X

- NOTES: UNLESS OTHERWISE SPECIFIED
- A) PACKAGE REFERENCE: JEDEC, DO-215 ISSUE D, VARIATION AD.
 - B) ALL DIMENSIONS ARE IN MILLIMETERS.
 - C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - E) DRAWING FILE NAME: MA02AREV3

APPROVALS		DATE	FAIRCHILD SEMICONDUCTOR™		
DRAWN: BOBOY MALDO		04AUG08	SOD-123, MOLDED, 2LD, JEDEC DO-214 VAR AD		
CHECKED: B.M. RULONA					
APPROVED: HENRY YANG					
HOWARD ALLEN					
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		NTS	N/A	MKT-MA02A	3
		FORMERLY: N/A			SHEET : 1 OF 1